

# SOT358-1

plastic low profile quad flat package; 32 leads; body 7 mm x 7 mm x 1.4 mm

19 July 2017

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	LQFP32
<b>Package type industry code</b>	LQFP32
<b>Package style descriptive code</b>	LQFP (low profile quad flat package)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	136E03
<b>JEDEC package outline code</b>	MS-026
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	9-11-2005
<b>Manufacturer package code</b>	SOT358

Table 1. Package summary

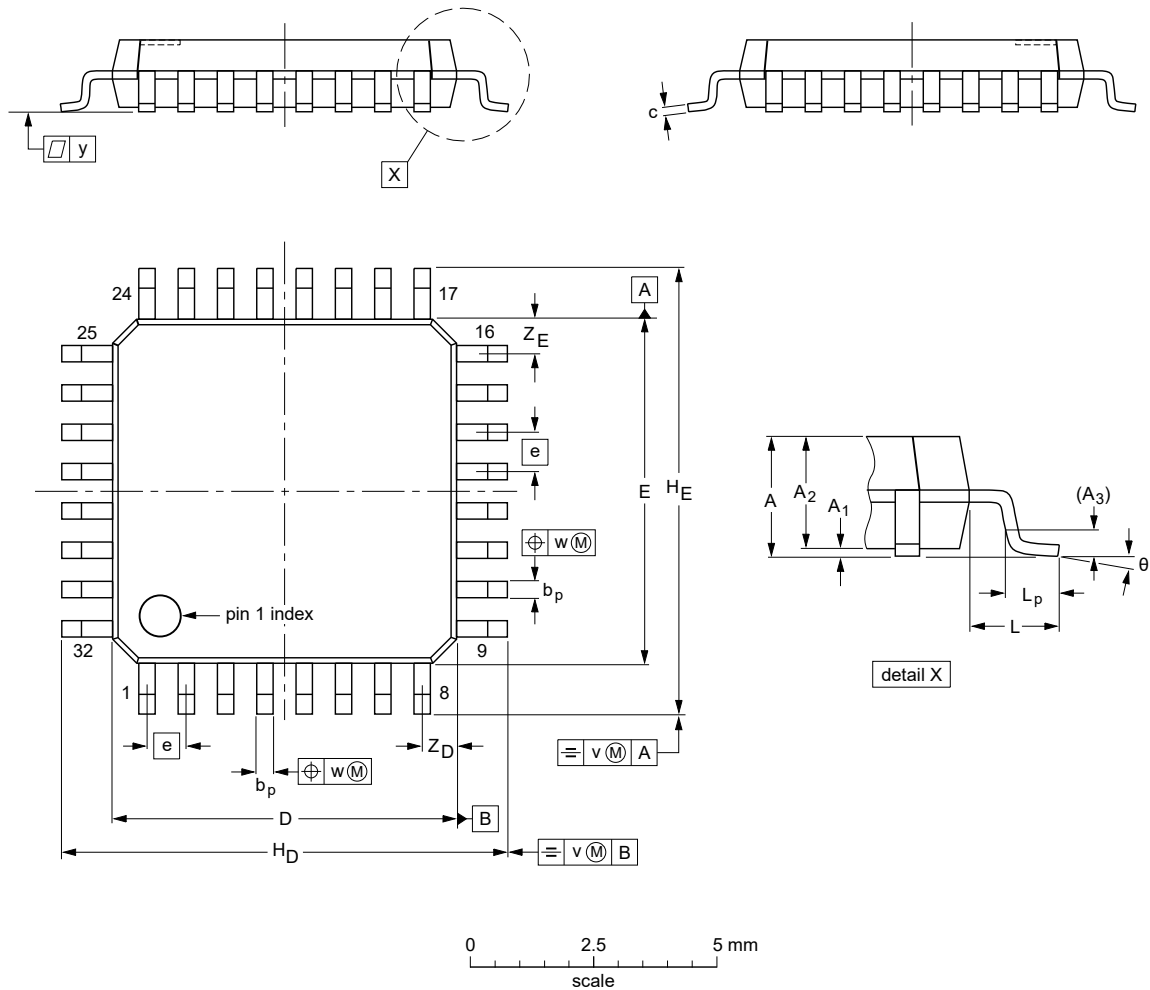
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	6.9	-	7	7.1	mm
E	package width	6.9	-	7	7.1	mm
A	seated height	-	-	1.6	1.6	mm
A <sub>2</sub>	package height	1.35	-	1.4	1.45	mm
e	nominal pitch	-	-	0.8	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	32	-	



## 2. Package outline

LQFP32: plastic low profile quad flat package; 32 leads; body 7 x 7 x 1.4 mm

SOT358-1



**DIMENSIONS (mm are the original dimensions)**

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>D</sub>	H <sub>E</sub>	L	L <sub>p</sub>	v	w	y	Z <sub>D</sub> <sup>(1)</sup>	Z <sub>E</sub> <sup>(1)</sup>	θ
mm	1.6	0.20 0.05	1.45 1.35	0.25	0.4 0.3	0.18 0.12	7.1 6.9	7.1 6.9	0.8	9.15 8.85	9.15 8.85	1	0.75 0.45	0.2	0.25	0.1	0.9 0.5	0.9 0.5	7° 0°

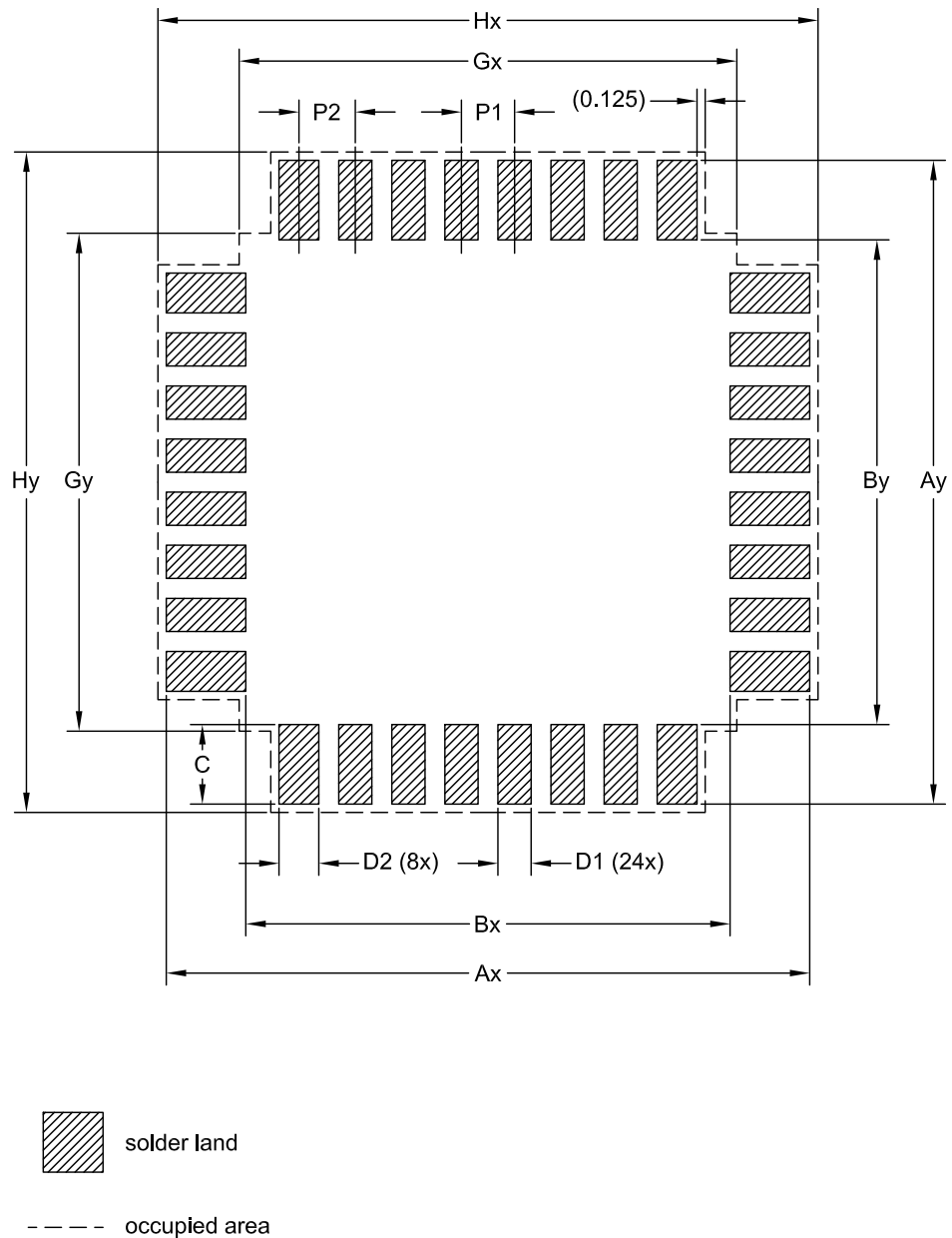
**Note**

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT358 -1	136E03	MS-026			03-02-25 05-11-09

Fig. 1. Package outline LQFP32 (SOT358-1)

### 3. Soldering

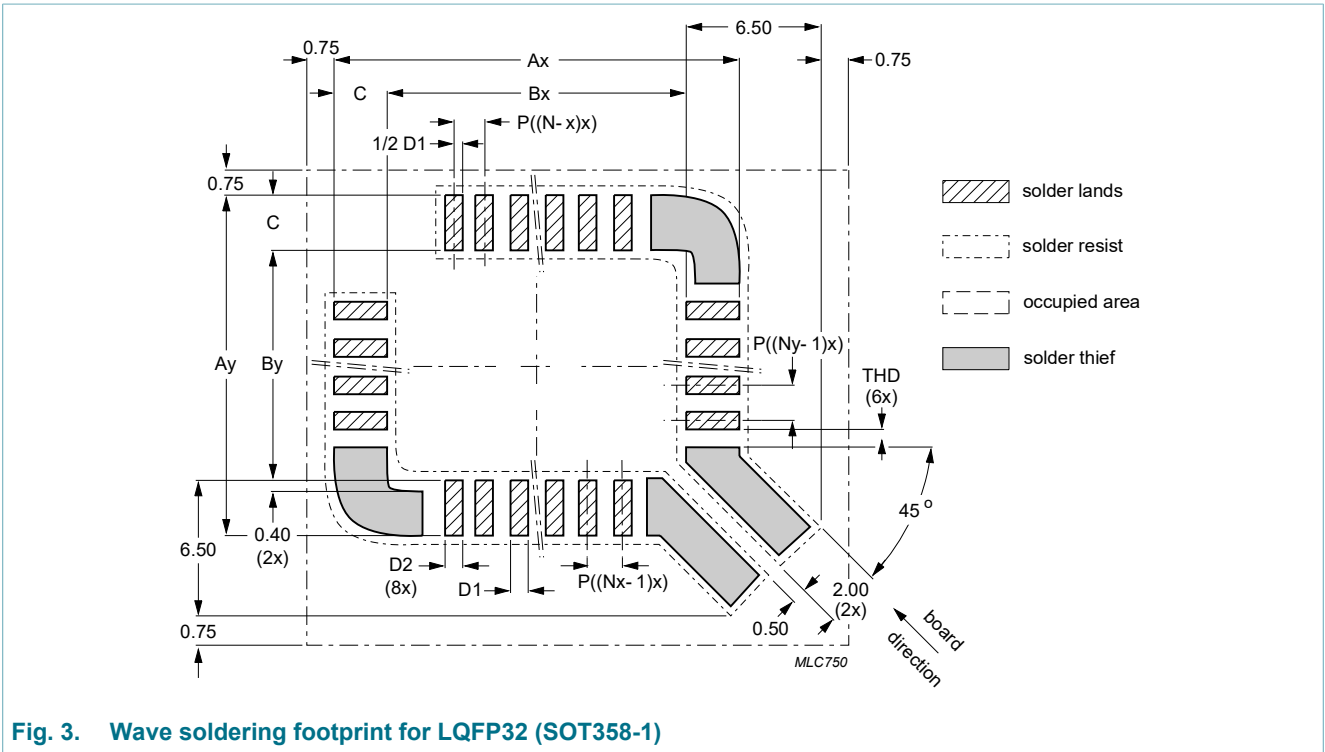


Dimensions in mm

P1	P2	Ax	Ay	Bx	By	C	D1	D2	Gx	Gy	Hx	Hy
0.800	0.850	9.700	9.700	7.300	7.300	1.200	0.500	0.600	7.500	7.500	9.950	9.950

Fig. 2. Reflow soldering footprint for LQFP32 (SOT358-1)

plastic low profile quad flat package; 32 leads; body 7 mm x 7 mm x 1.4 mm



## 4. Legal information

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